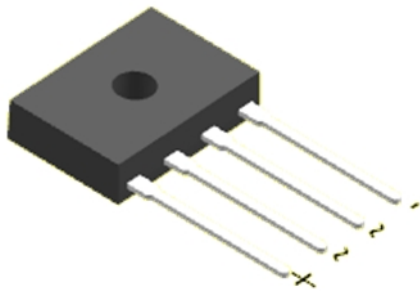


**GBP**



**Features**

- ROHS compliant
- Glass passivated chip
- High forward surge capability
- Meet MSL level 1, per J-STD-020 LF maximum peak of 250 °C
- Solder dip 260 °C / 40S
- Component in accordance to ROHS 2002/95/EC and WEEE 2002/96/WC
- UL recognition, file number E342874



**Primary characteristics**

$I_{F(AV)}$	2A
$V_{RRM}$	600V to 1000V
$I_{FSM}$	65A
$I_{RM}$	5uA
$V_{FM}$ at $I_F=1A$	1.05V
$T_J$ max.	150 °C

**Applications**

Ideal for ac-to-dc bridge full wave rectification such as SMPS, home appliances, office equipment, industrial automation applications

**Mechanical data**

- Case: GBP
- Epoxy meets UL 94 V-0 flammability rating
- Terminals: Tin plated leads.
- Polarity: As marked.
- Mounting Torque: 10cm·kg(8.8 inches·lbs)max.
- Recommended Torque: 5.7 cm·kg(5 inches·lbs)

**Maximum rating (Ta=25°C unless otherwise noted)**

Parameter	Sym	GBP			Unit
		206	208	210	
Max. repetitive peak reverse voltage	$V_{RRM}$	600	800	1000	V
Max. RMS reverse voltage	$V_{RMS}$	420	560	700	V
Max. DC blocking voltage	$V_{DC}$	600	800	1000	V
Max. average forward current	$I_{F(AV)}$	2			A
Non-repetitive peak forward surge current 8.3ms single half-sine-wave	$I_{FSM}$	65			A
Rating for fusing, $1ms \leq t \leq 8.3ms$	$I^2t$	16			A <sup>2</sup> S
Max. instantaneous forward voltage drop per diode	$V_{FM}$	1.05 (1A)			V
Max. instantaneous reverse current at rated DC blocking voltage	$I_{RM}$	Ta=25 °C	5		µA
		Ta=125 °C	500		µA
Operating junction temperature	$T_J$	-55 ~ +150			°C
Storage temperature	$T_{STG}$	-55 ~ +150			°C
Thermal resistance junction to cover (Note1)	$R_{J-C}$	3			°C/W
Typical junction capacitance (Note 2)	$C_J$	25			pF

**Notes**

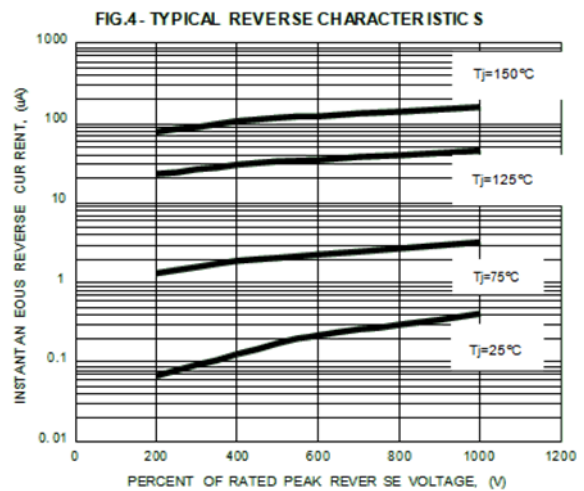
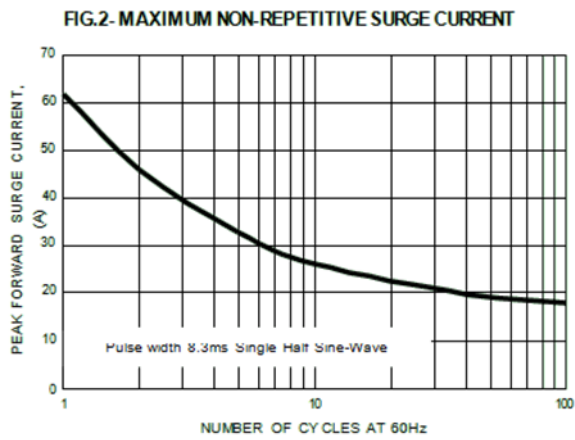
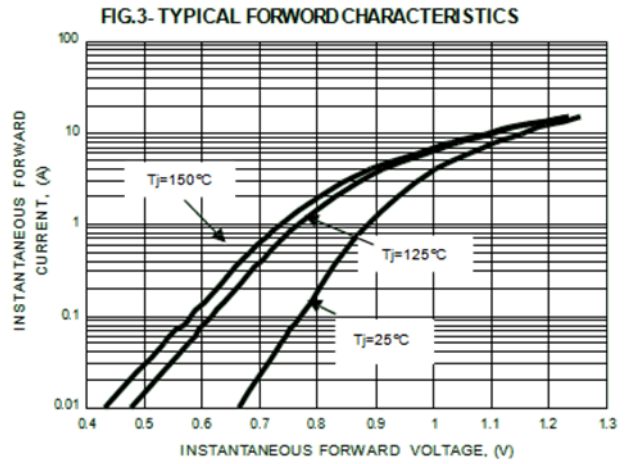
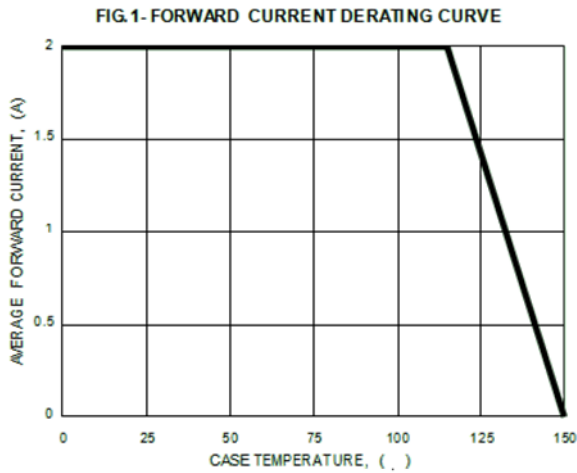
- (1) Device mounted on 50mm x 50mm x 1.6mm Cu Plate Heatsink
- (2) Measured at 1.0 MHz and applied reverse voltage of 4.0 Volts



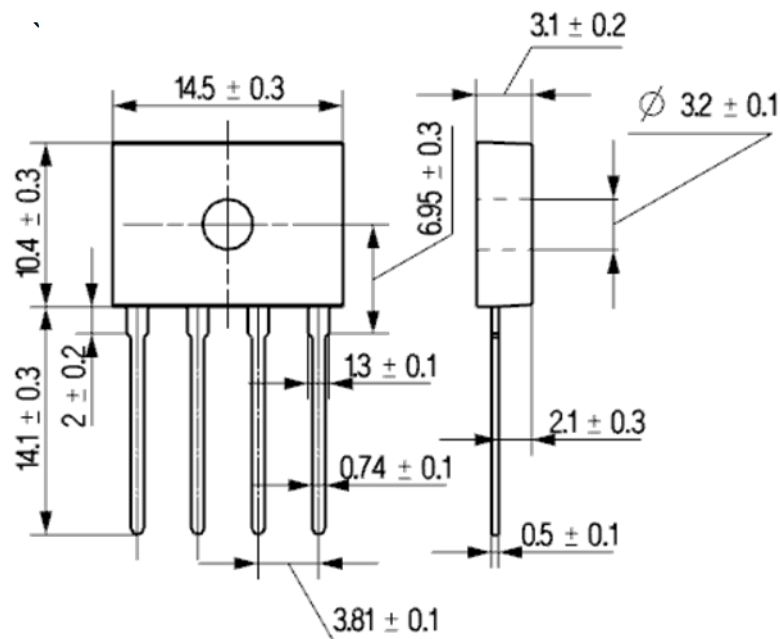
**Ordering information (Example)**

PREFERRED	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
GBP206				

**Typical characteristics**



**Package outline dimensions**



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